

N and P-Channel Enhancement Mode Power MOSFET

Description

The NCE609 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

● N-Channel

$$V_{DS} = 40V, I_D = 21A$$

$$R_{DS(ON)} < 17m\Omega @ V_{GS} = 10V$$

$$R_{DS(ON)} < 29m\Omega @ V_{GS} = 4.5V$$

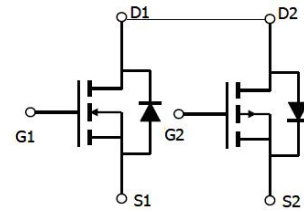
● P-Channel

$$V_{DS} = -40V, I_D = -14A$$

$$R_{DS(ON)} < 32m\Omega @ V_{GS} = -10V$$

$$R_{DS(ON)} < 45m\Omega @ V_{GS} = -4.5V$$

- High power and current handling capability
- Lead free product is acquired
- Surface mount package



Schematic diagram



Marking and pin assignment

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE609	NCE609	TO-252-4L	-	-	-

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	40	-40	V
Gate-Source Voltage	V_{GS}	± 25	± 25	V
Continuous Drain Current	I_D	21	-14	A
		17.5	-11.5	
Pulsed Drain Current (Note 1)	I_{DM}	84	-56	A
Maximum Power Dissipation	P_D	40	40	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	-55 To 150	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	N-Ch	3.1	$^\circ C/W$
Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	P-Ch	3.1	$^\circ C/W$

N-CH Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.6	2.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A	-	14	17	mΩ
		V _{GS} =4.5V, I _D =5A	-	19	29	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =10A		15	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, F=1.0MHz	-	1110	-	PF
Output Capacitance	C _{oss}		-	114	-	PF
Reverse Transfer Capacitance	C _{rss}		-	109	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =20V, R _L =2Ω V _{GS} =10V, R _{GEN} =3Ω	-	4	-	nS
Turn-on Rise Time	t _r		-	11.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	18	-	nS
Turn-Off Fall Time	t _f		-	5.6	-	nS
Total Gate Charge	Q _g	V _{DS} =20V, I _D =10A, V _{GS} =10V	-	30	-	nC
Gate-Source Charge	Q _{gs}		-	5	-	nC
Gate-Drain Charge	Q _{gd}		-	7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =10A	-	0.8	1.2	V

P-CH Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.6	-2.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-7A	-	27	32	mΩ
		V _{GS} =-4.5V, I _D =-4A	-	34	45	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-7A	-	15	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V, F=1.0MHz	-	1139	-	PF
Output Capacitance	C _{oss}		-	114	-	PF
Reverse Transfer Capacitance	C _{rss}		-	103	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-20V, R _L =2.3Ω V _{GS} =-10V, R _{GEN} =6Ω	-	10	-	nS
Turn-on Rise Time	t _r		-	15	-	nS
Turn-Off Delay Time	t _{d(off)}		-	30	-	nS
Turn-Off Fall Time	t _f		-	18	-	nS
Total Gate Charge	Q _g	V _{DS} =-20V, I _D =-7A V _{GS} =-10V	-	22.5	-	nC
Gate-Source Charge	Q _{gs}		-	2.4	-	nC
Gate-Drain Charge	Q _{gd}		-	5.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =-14A	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

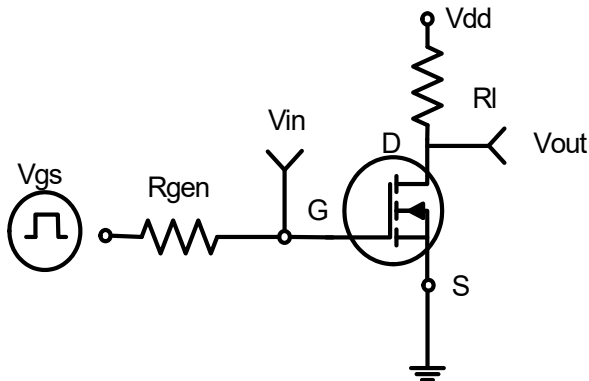


Figure 1: Switching Test Circuit

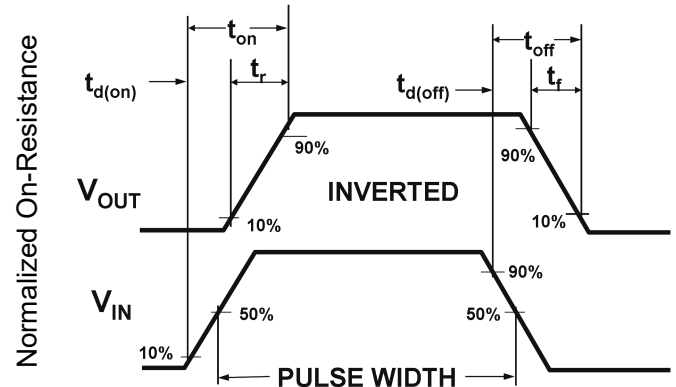


Figure 2: Switching Waveforms

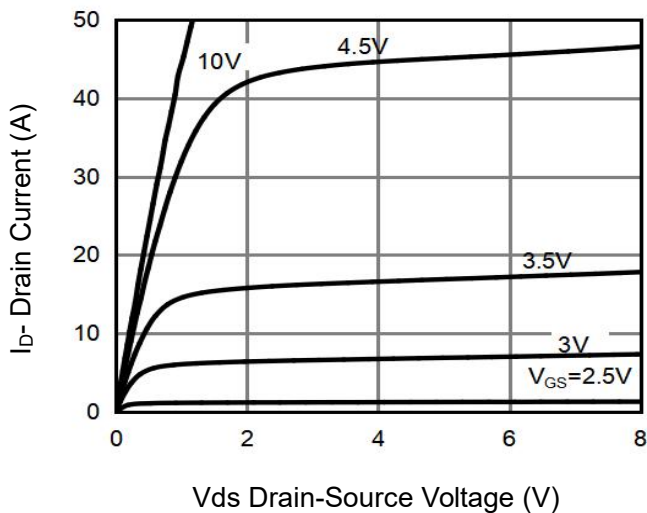


Figure 3 Output Characteristics

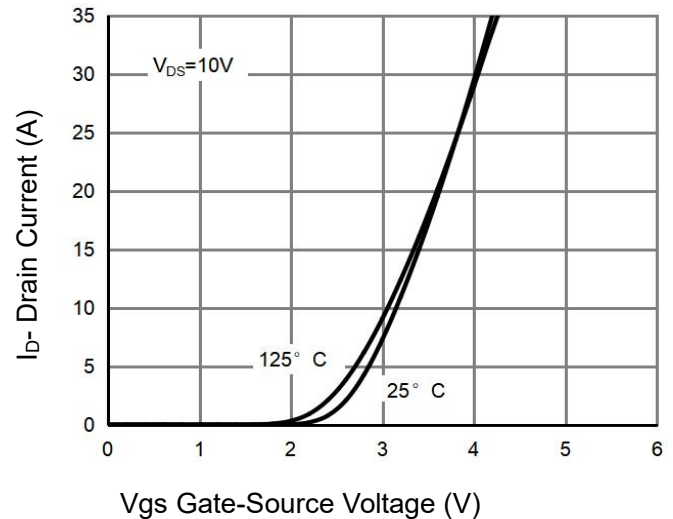


Figure 4 Transfer Characteristics

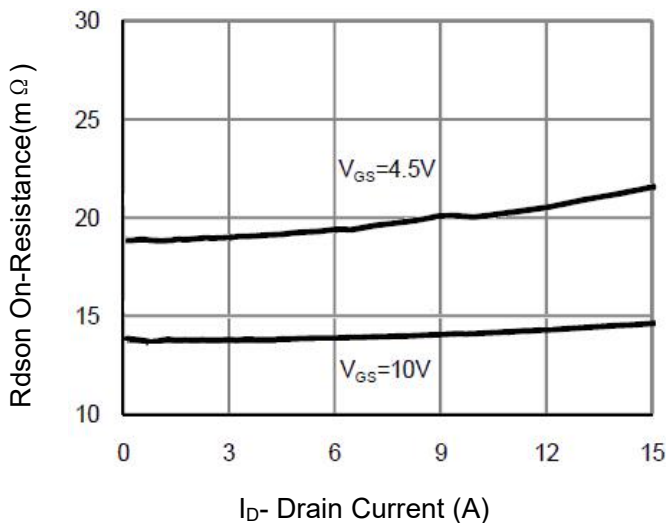


Figure 5 Drain-Source On-Resistance

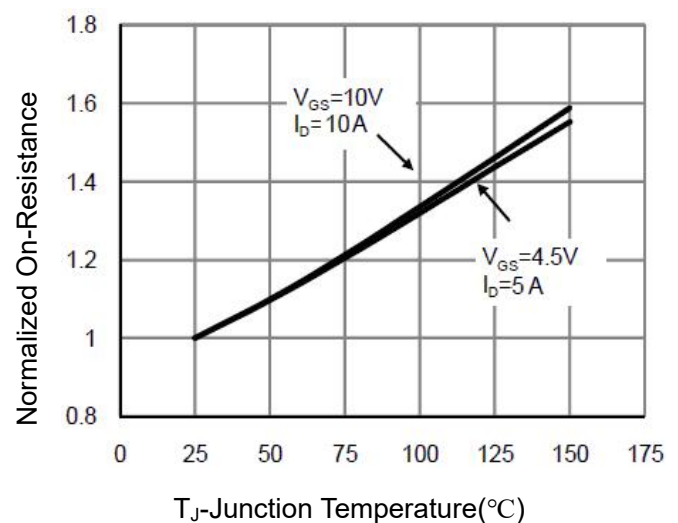


Figure 6 Drain-Source On-Resistance

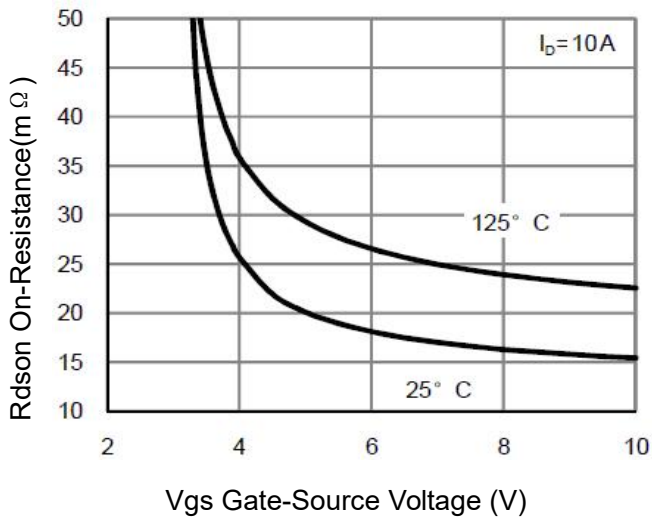


Figure7 Rdson vs Vgs

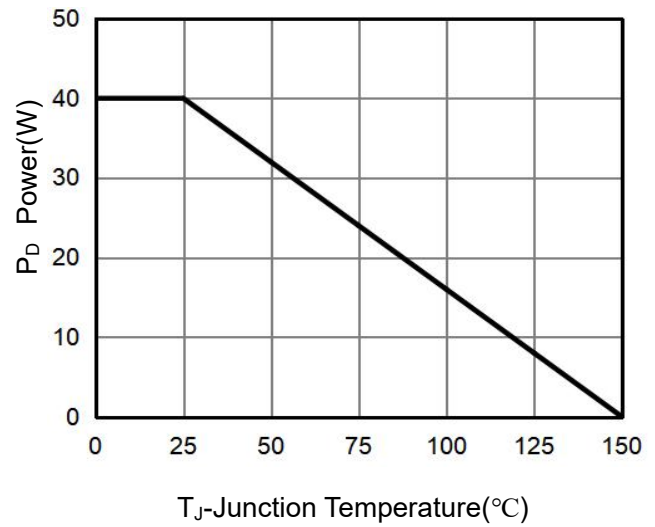


Figure 8 Power Dissipation

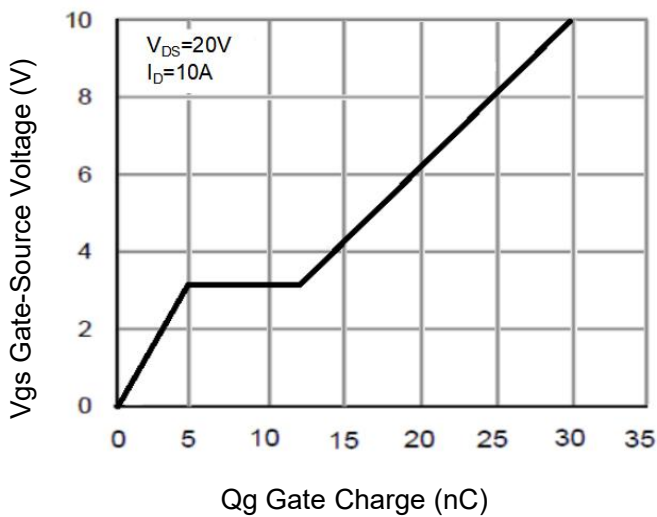


Figure 9 Gate Charge

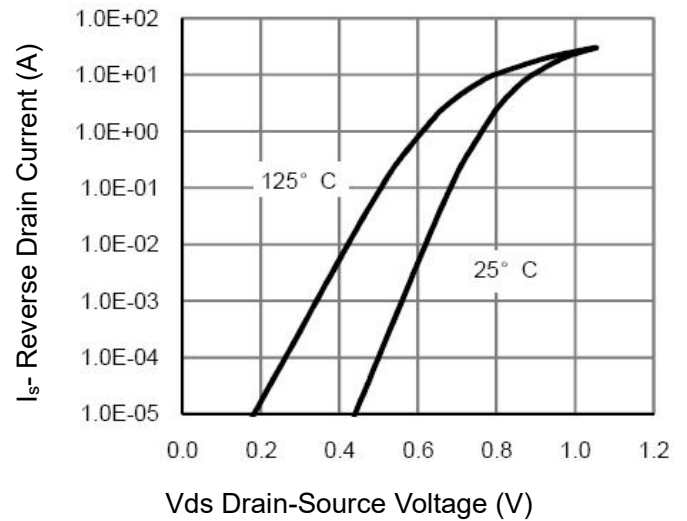


Figure 10 Source- Drain Diode Forward

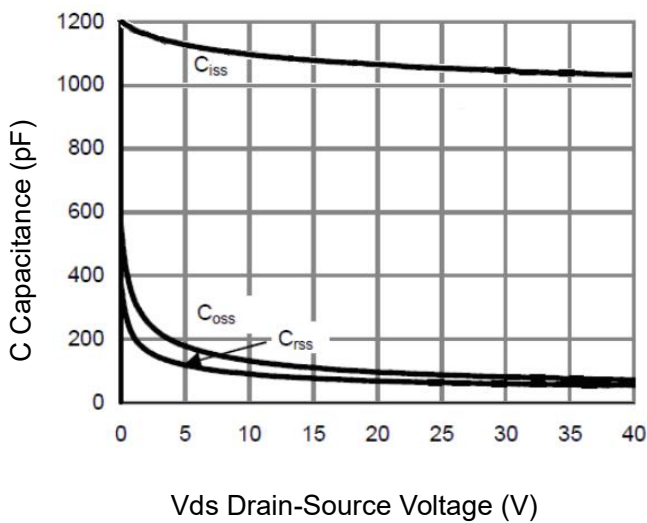


Figure 11 Capacitance vs Vds

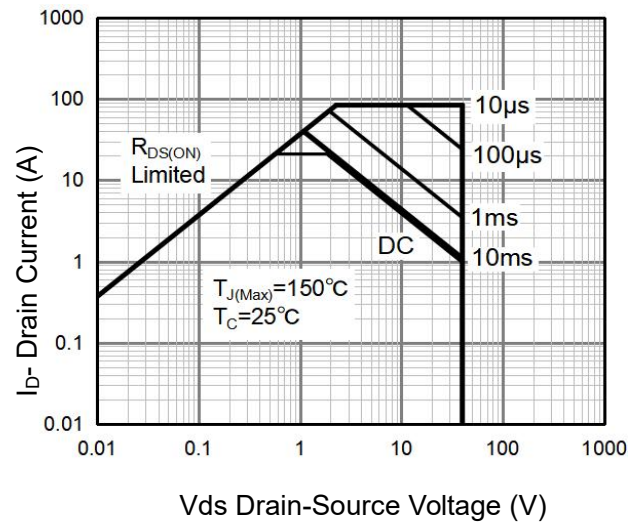


Figure 12 Safe Operation Area

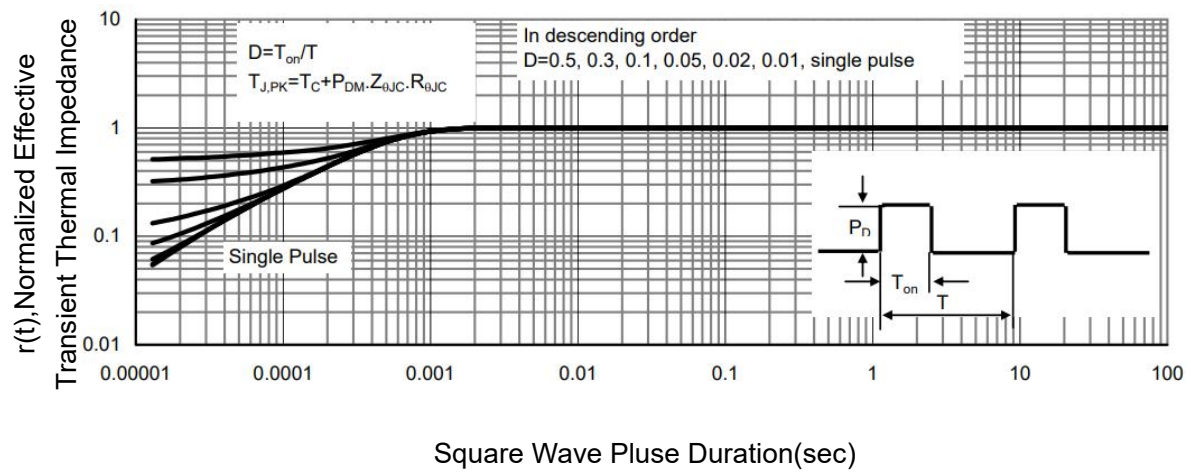


Figure 13 Normalized Maximum Transient Thermal Impedance

P- Channel Typical Electrical and Thermal Characteristics (Curves)

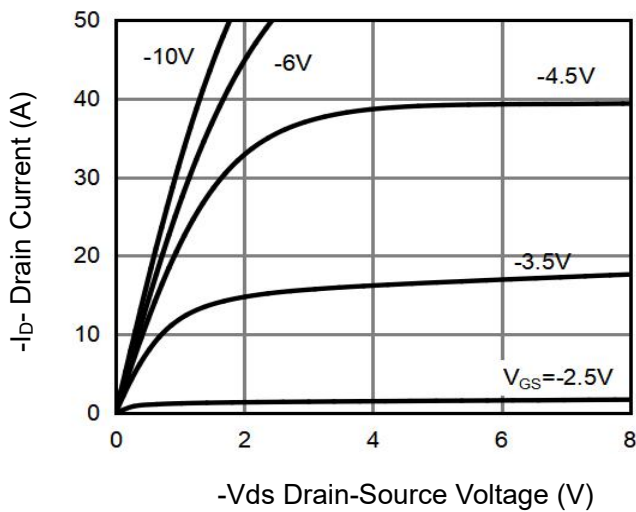


Figure 1 Output Characteristics

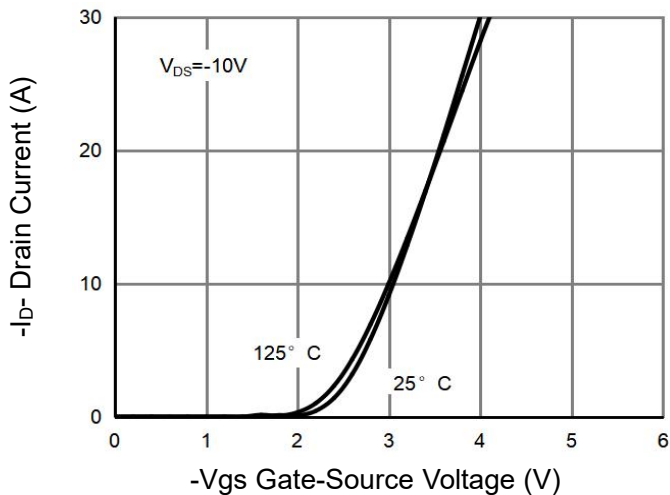


Figure 2 Transfer Characteristics

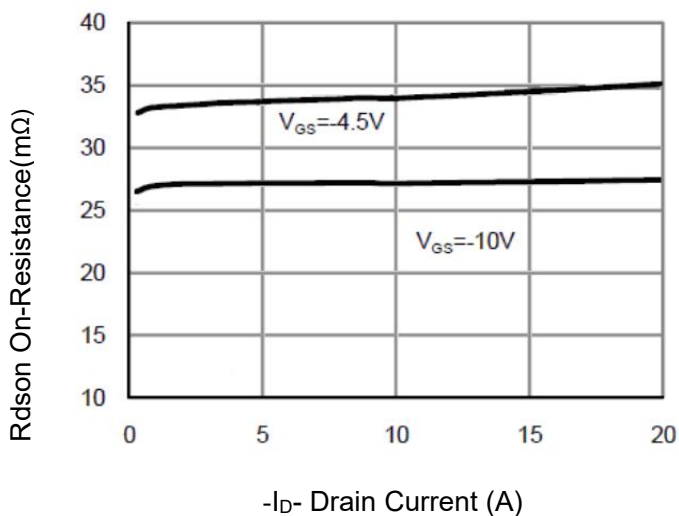


Figure 3 Rdson- Drain Current

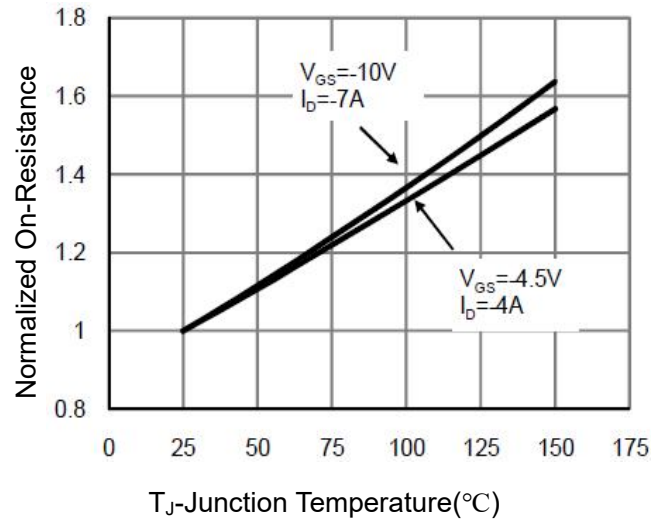


Figure 4 Rdson-Junction Temperature

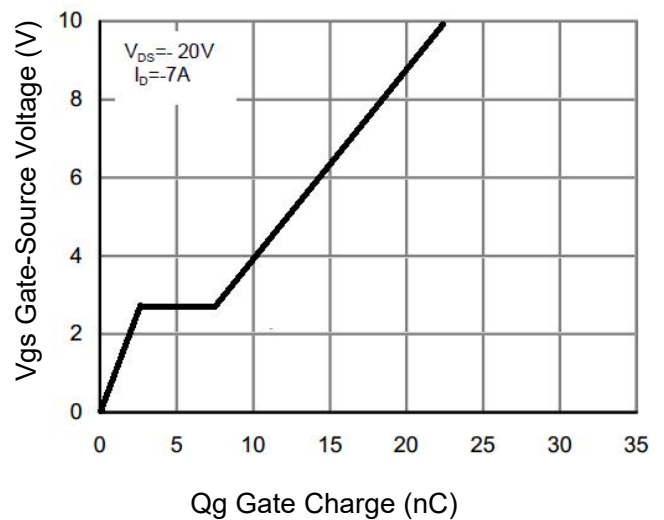


Figure 5 Gate Charge

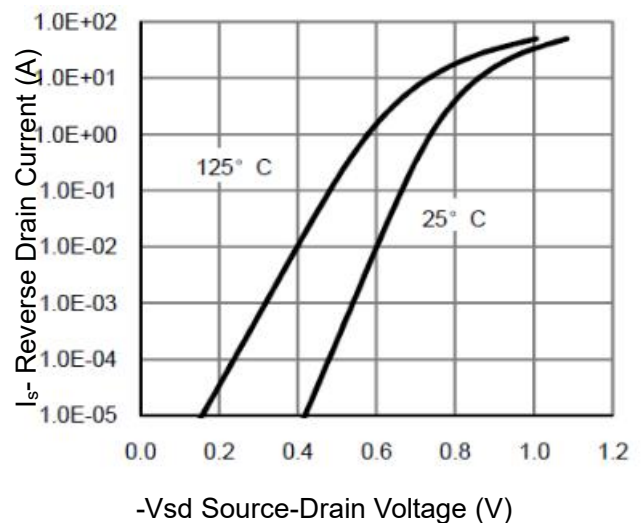
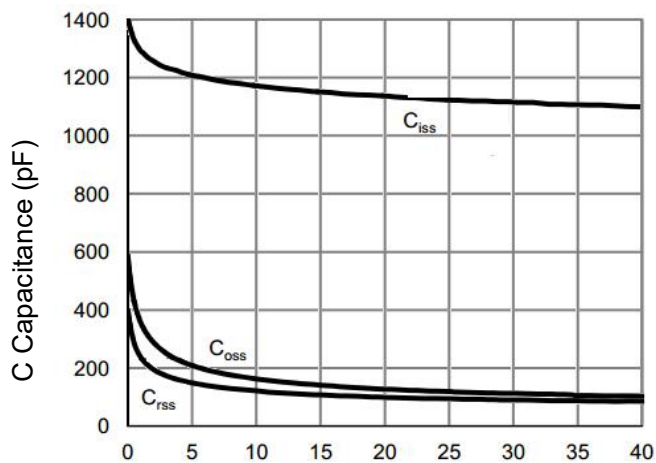
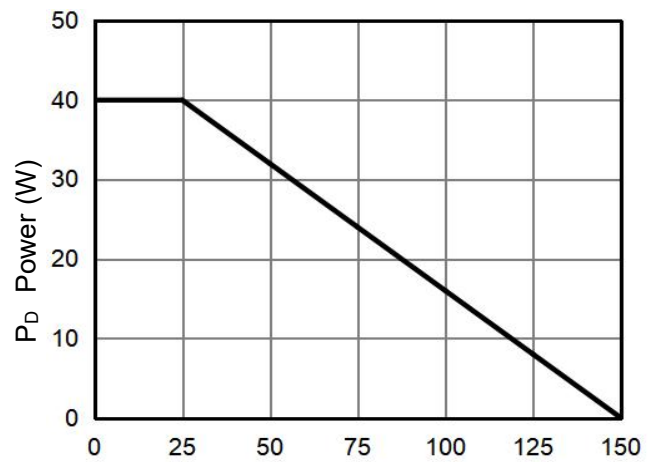


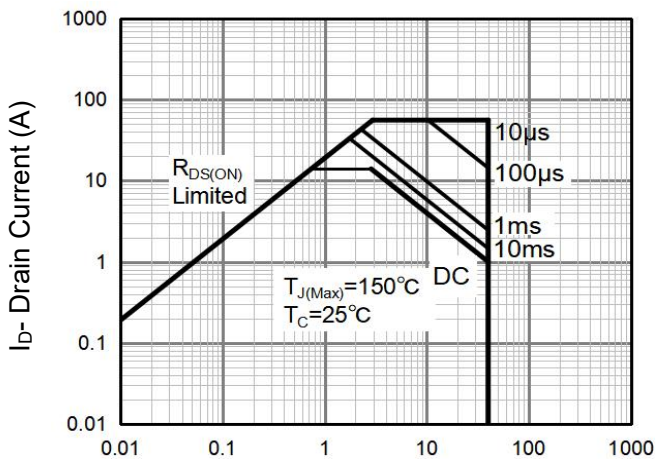
Figure 6 Source- Drain Diode Forward



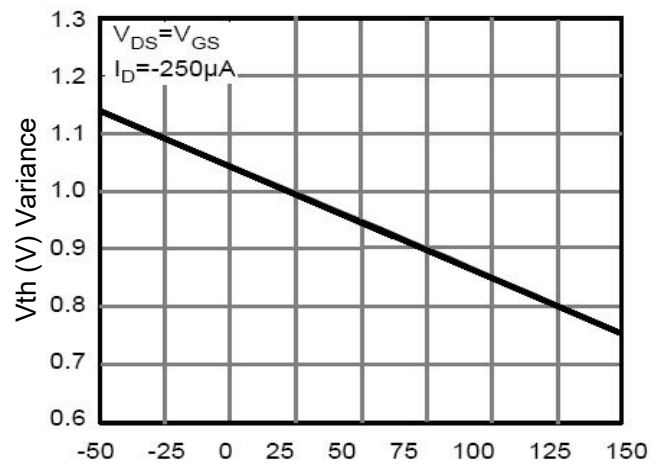
-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



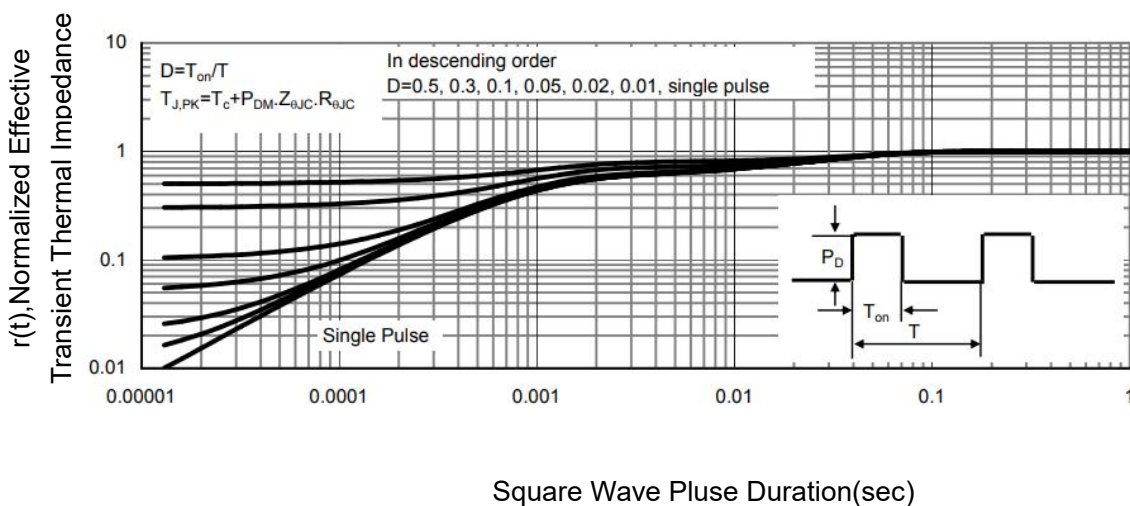
Tj-Junction Temperature(°C)
Figure 9 Power Dissipation



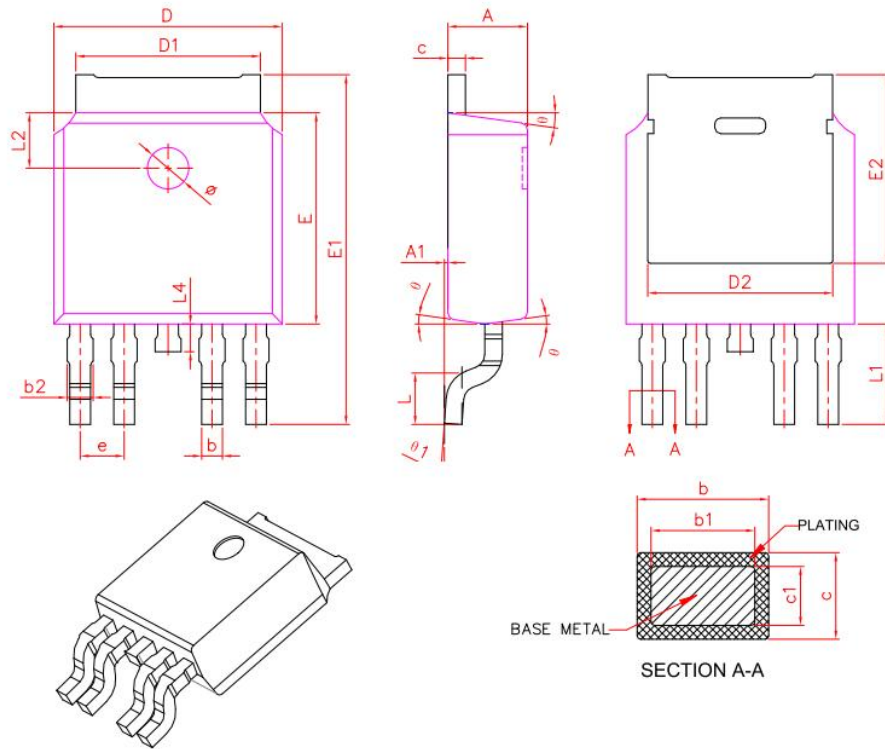
-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



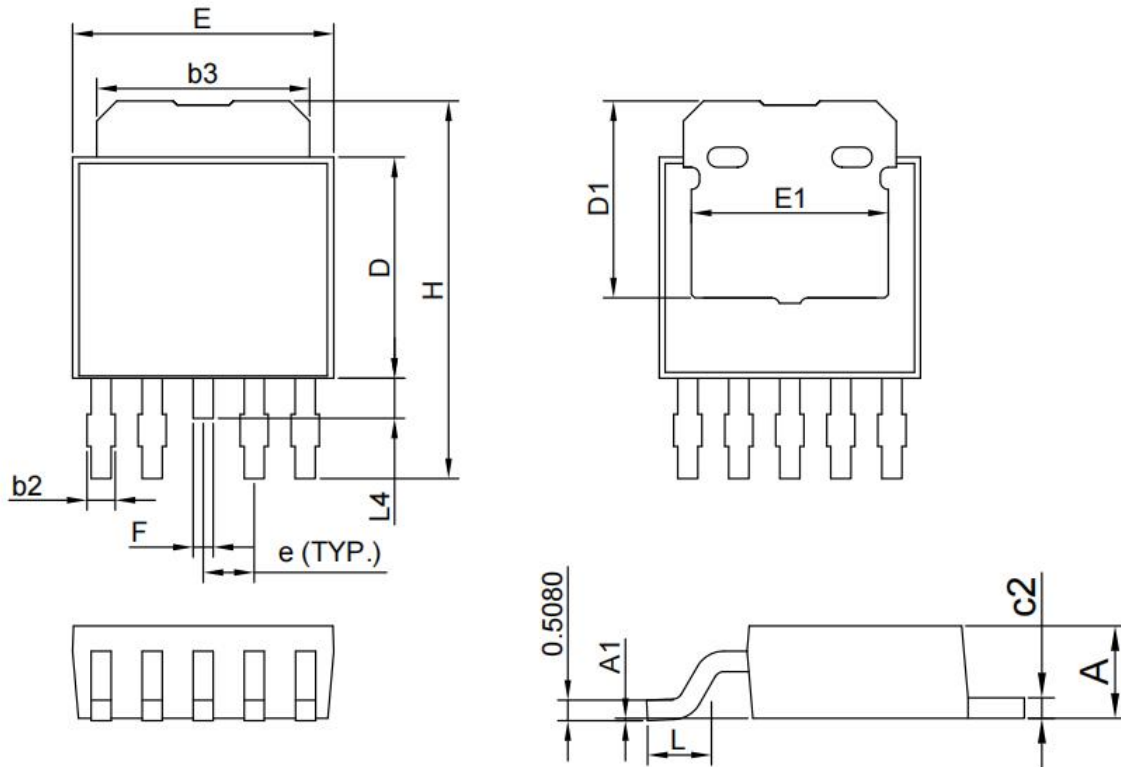
Tj-Junction Temperature(°C)
Figure 10 V_{GS(th)} vs Junction Temperature



Square Wave Pluse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-4L (E) Package Information


T0252-4L			
DIM.	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A1	0.00	0.08	0.13
b	0.50	0.60	0.70
b1	0.57	0.60	0.63
b2	0.75REF		
c	0.46	0.508	0.58
c1	0.50	0.508	0.52
D	6.50	6.60	6.70
D1	5.10	5.334	5.46
D2	5.346REF		
E	6.00	6.10	6.20
E1	9.80	10.10	10.40
E2	5.446REF		
e	1.17	1.27	1.37
L	1.40	1.50	1.70
L1	2.90REF		
L2	1.60REF		
L4	0.60	0.80	1.00
φ	φ1.10	φ1.20	φ1.30
θ	5°	8°	10°
θ1	0°	—	8°
All dimensions in millimeters			

TO-252-4L (X) Package Information

COMMON DIMENSIONS
 UNITS OF MEASURE=MILLIMETER

SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	0.08	0.15
b	0.45	0.53	0.60
b2	0.50	0.65	0.80
b3	5.20	5.35	5.50
c2	0.45	0.50	0.55
D	5.40	5.60	5.80
D1	4.57	—	—
E	6.40	6.60	6.80
E1	3.81	—	—
e	1.27 REF.		
F	0.40	0.50	0.60
H	9.40	9.80	10.20
L	1.40	1.59	1.77
L1	2.40	2.70	3.00
L2	0.80	1.00	1.20

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